˴ ˎ ˚ Ŀ ̃Ǫ ╚ ‖ ㄱ ı ɾ ᵇ ɔ я χ 83Y¢4333Y ı* ᵇ ɔ ╚ χ 4⁞3D ı V P D Ṃ Ŀ
Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage χ 50 to1000V,Forward Current:1.0A ,SMA package.

ㅓ אַ ק ל ᑕ ı ή ؤ ㅓ ᵀ ℌ ` UrKV ˝Yɒ 53442982HX ı گ ŧ ˴ ˎ ˚ Ŀ ı ㅓ ᵀ DHF0T434 ‰ ´ ב ׀ ، ό ɭ ∂ ı ή ғ β
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65ithoƐEU directives, For surface mounted applications, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

˜ ŧ ∪ ı ◗ ′ ∩ ح Ẕ ŧ ⊠ Ⱨ ɭ ∂

| v Ѭ<br>Parameter | ч N<br>Symbol | Ѭ Ө<br>Rating | | | | | | | D Ч<br>Unit |
|---|---|---|---|---|---|---|---|---|---|
| | | BRM1Q | BRM2Q | BRM3Q | BRM4Q | BRM5Q | BRM6Q | BRM7Q | |
| Maximum Repetitive Peak Reverse Voltage | $V_{RRM}$ | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | $V_{RMS}$ | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | $V_{DC}$ | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum Average Forward Rectified Current @ Fig.1 | | | | | | | | | |

## / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

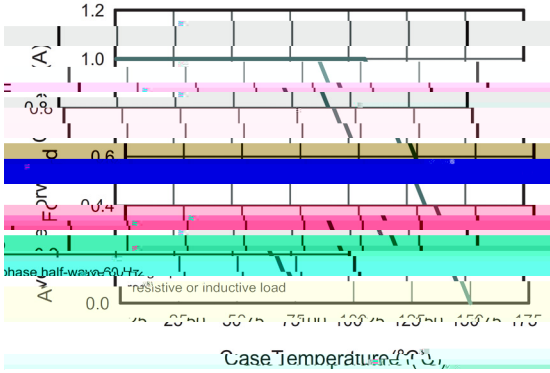



Fig.2 Typical Reverse Characteristics

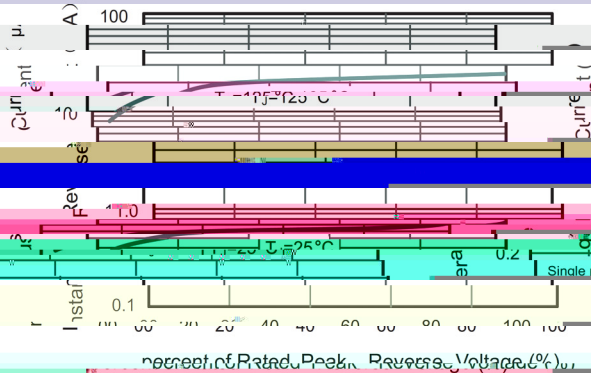



Fig.3 Typical Forward Characteristic

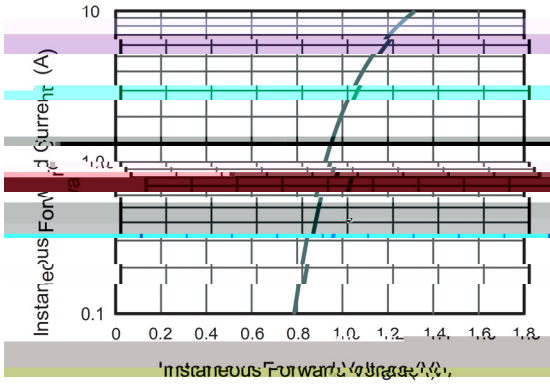



Fig.4 Typical Junction Capacitance

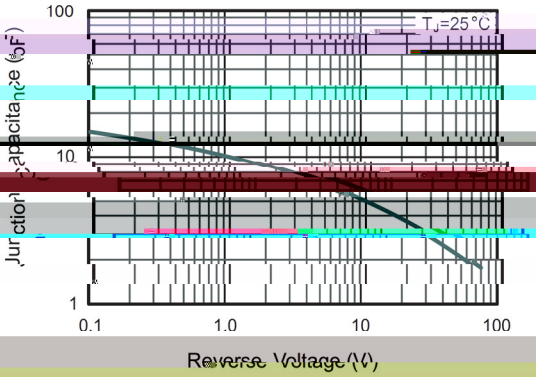
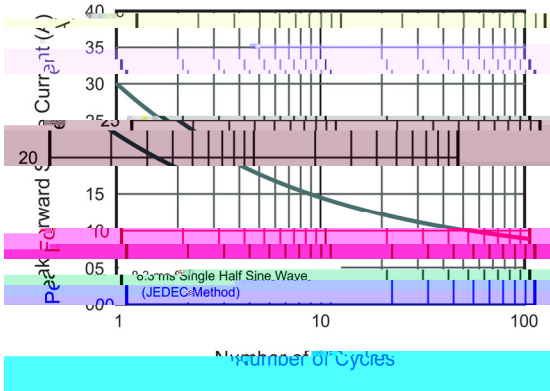



Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



## / Package Dimensions



## / Marking Instructions




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P : χ ѭ ʒ ᴺ Ղ

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**** χ ѭ ı ꜰ ñ ᴺ Ղ ı ₲ ı ꜰ ñ ᴺ Ψ ק

Note:

P : χ Product Type Code

Q: Automobile halogen-free product Code

**** χ Lot No. Code, code change with Lot No

## Marking

| Type number | Marking code |
|---|---|
| BRM1Q | M1Q |
| BRM2Q | M2Q |
| BRM3Q | M3Q |
| BRM4Q | M4Q |
| BRM5Q | M5Q |
| BRM6Q | M6Q |
| BRM7Q | M7Q |

## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

| |
|---|
| |
| |
| |
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| |
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| |

ب ˝ χ

1 Ĺ ♬ □ ỷ 150 Ḱ 200 ɬ ı `H ڑ 60 Ḱ 120sec;

2 Š Ө □ ỷ 255 ° 5 ɬ ı `H ڑ 'Y ʌ ʁ 5 ° 0.5sec;

3 ì ˙ ٢ ˛ ɔ ♨ ỷ ʁ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:150~200 ɬ , Time:60~120sec.

2.Peak Temp.:255 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

## / Resistance to Soldering Heat Test Conditions

| | | | |
|---|---|---|---|
| □ ỷ χ 260 ° 5 ɬ | `H ڑ χ 10 ° 1 sec. | Temp.:260±5 | Time:10±1 sec |

## / Packaging SPEC.

ი ` ɣ Ь / REEL

| Package Type | Units | Dimension | (unit mm³) |
|---|---|---|---|